



**FOR IMMEDIATE RELEASE**

**EV GROUP WINS 3D INCITES “EQUIPMENT SUPPLIER OF THE YEAR” AWARD**

*Prestigious industry award recognizes EVG’s significant contributions to the advancement of the 3D-IC packaging and heterogeneous integration roadmap*

**ST. FLORIAN, Austria, March 4, 2020**—EV Group (EVG), a leading supplier of wafer bonding and lithography equipment for the MEMS, nanotechnology and semiconductor markets, today announced that it has received the prestigious 2020 *3D InCites* Award in the category of “Equipment Supplier of the Year” in recognition of its SmartView<sup>®</sup> NT3 automated bond alignment system. Available on EVG’s GEMINI<sup>®</sup> FB XT integrated fusion bonding platform for high-volume manufacturing applications, the SmartView NT3 aligner provides unmatched wafer bonding performance to meet future 3D-IC packaging requirements.

Hosted by [3D InCites](#), an online media resource founded in 2009 to stir up interest in 3D integration, the *3D InCites* Awards program recognizes significant contributions to the advancement of the heterogeneous roadmap, including 3D packaging, interposer integration, advanced fan-out wafer-level packaging, MEMS and sensors, and full system integration.

EVG has been providing solutions for advanced packaging and heterogeneous integration for more than 20 years, supporting revolutionary technology advances such as backside-illuminated CMOS image sensors (BSI-CIS), 3D/stacked die packaging, as well as ultra-thin and stacked fan-out packages. The company’s industry-leading wafer bonding, thin-wafer handling, and lithography products are supported by EVG’s newly announced [Heterogeneous Integration Competence Center™](#), which is designed to assist customers in leveraging EVG’s process solutions and expertise to enable new and enhanced products and applications driven by advances in system integration and packaging.

“It’s a true honor for EVG to be recognized by industry experts and peers for our contributions to heterogeneous integration,” stated Hermann Watti, executive sales and customer support director at EV Group. “We are proud of our decades-long commitment to the semiconductor packaging industry, working tirelessly to bring to market innovative process solutions that support our customers’ need for greater design flexibility, increased performance and lower design and system cost. The SmartView NT3 aligner is just one of our latest breakthrough products introduced over the years to extend customers’ roadmaps. For example, the SmartView NT3 aligner in combination with our GEMINI FB XT provided the first demonstration of sub-100-nm wafer-to-wafer alignment overlay for hybrid bonding—enabling devices such as 3D BSI-CIS and memory-on-logic stacking.”

The SmartView NT3 aligner was developed specifically for fusion and hybrid wafer bonding. It enables stacked devices with greater density and performance, lower power consumption and smaller footprint. It provides sub-50-nm wafer-to-wafer alignment accuracy (a 2-3X improvement) as well as significantly higher throughput compared to the previous-generation platform. Applications include flash memory stacking, 3D SoC, stacked backside illuminated CMOS image sensors, and die partitioning.

For more information on the SmartView NT family of automated bond alignment systems, please visit <https://www.evgroup.com/products/bonding/bond-alignment-systems/smartview-nt/>.



**EV GROUP RECEIVES PRESTIGIOUS 3D INCITES AWARD FOR BEST EQUIPMENT SUPPLIER OF THE YEAR.....Page 2 of 2**

**About EV Group (EVG)**

EV Group (EVG) is a leading supplier of equipment and process solutions for the manufacture of semiconductors, microelectromechanical systems (MEMS), compound semiconductors, power devices and nanotechnology devices. Key products include wafer bonding, thin-wafer processing, lithography/nanoimprint lithography (NIL) and metrology equipment, as well as photoresist coaters, cleaners and inspection systems. Founded in 1980, EV Group services and supports an elaborate network of global customers and partners all over the world. More information about EVG is available at [www.EVGroup.com](http://www.EVGroup.com).

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